



Information & Control Japan TC Chapter Meeting

Japan Standards Winter 2018 Meetings in conjunction with SEMICON Japan 2018

Friday, December 14, 2018

Tokyo Big Sight, Tokyo, Japan

13:00 - 17:00

AGENDA (Draft)

1 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines)

1.3 Agenda Review

2 Technical Committee Awards

3 Review of Previous Meeting

3.1 Review and Approval of Previous Meeting Minutes

3.2 Action Items from the previous meeting

4 Liaison Report

4.1 Europe

4.2 Korea

4.3 North America

4.4 Taiwan

4.5 Staff Report

5 Ballot Review

5.1 Line Item revision to SEMI E5-1217: Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II)

6 Subcommittee & Task Force Reports

6.1 GEM300 TF

6.2 Japan I&C Maintenance TF

6.3 Sensor Bus TF

6.4 Diagnostic Data Acquisition (DDA) TF

6.5 Fab & Equipment Information Security Task Force

6.6 Equipment Data Acquisition (EDA) Working Group

7 Old Business

- 7.1 SNARF Project Period Check
- 7.2 5 Year Review Check
- 7.3 EDA Workshop at SEMICON Japan 2018

8 New Business

- 8.1 Editorial Changes for SEMI E54.21-1110 (Reapproved 0517) Specification For Sensor Actuator Network For Motionnet® Communication
- 8.2 Result of R6375: Revision to: 'SEMI E170-1217: Specification for Secured Foundation of Recipe Management System (SFORMS)', and 'SEMI E170.1-1217: Specification for SECS-II Protocol for Secured Foundation of Recipe Management System'
- 8.3 TFOF for Japan Advanced Back-end Factory Integration TF (TF Name is tentative)

9 Action Item Review

- 9.1 Open Action Items
- 9.2 New Action Items

10 Next Meeting and Adjournment